



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD60R360P7		<b>Issued</b>		19. January 2018		
<b>MA#</b>		MA001976884						
<b>Package</b>		PG-TO252-3-342		<b>Weight*</b>		334.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.321	0.69	0.69	6945	6945
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.02		161	
	non noble metal	iron	7439-89-6	0.180	0.05		537	
	non noble metal	copper	7440-50-8	179.273	53.65	53.72	536484	537182
	non noble metal	aluminium	7429-90-5	0.450	0.13	0.13	1346	1346
wire	non noble metal	aluminium	7429-90-5	0.450	0.13	0.13	1346	1346
encapsulation	organic material	carbon black	1333-86-4	1.162	0.35		3478	
	plastics	epoxy resin	-	16.269	4.87		48686	
	inorganic material	silicondioxide	60676-86-0	127.829	38.25	43.47	382536	434700
leadfinish	non noble metal	tin	7440-31-5	3.740	1.12	1.12	11192	11192
plating	non noble metal	nickel	7440-02-0	0.523	0.16	0.16	1566	1566
solder	non noble metal	tin	7440-31-5	0.047	0.01		141	
	noble metal	silver	7440-22-4	0.059	0.02		177	
	non noble metal	lead	7439-92-1	2.256	0.68	0.71	6751	7069
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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